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Product Change Notification - JAON-20TVFV764 [\(Printer Friendly\)](#)

**Date:** 27 Nov 2015

**Notification subject:** CCB 1787 Initial Notice: Qualification of ASE site for LAN9311 and LAN9313 device families in 128L TQFP package using CuPdAu wire, C7025 lead frame, CRM-1076 die attach and G631H molding compound.

**Notification text:** **PCN Status:**  
Initial notification

**Microchip Parts Affected:**  
Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**  
Qualification of ASE assembly site for LAN9311 and LAN9313 device families available in 128L TQFP package using palladium coated copper with gold flash (CuPdAu) bond wire, C7025 lead frame, CRM-1076 die attach and G631H molding compound material.

**Pre Change:**  
Assembled at ATT assembly site using Gold (Au) bond wire, C194 lead frame, 3230 die attach and G700L molding compound material

**Post Change:**  
Assembled at ASE assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, C7025 lead frame, CRM-1076 die attach and G631H molding compound material

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	ATT assembly site	ASE assembly site
<b>Wire material</b>	Au wire	CuPdAu wire
<b>Die attach material</b>	3230	CRM-1076
<b>Molding compound material</b>	G700L	G631H
<b>Lead frame material</b>	C194	C7025

**Impacts to Data Sheet:**  
None

**Reason for Change:**  
To improve Improve On-Time Delivery Performance by qualifying ASE assembly site.

**Change Implementation Status:**  
In Progress

**Estimated First Ship Date:**  
March 15, 2016 (date code: 1611)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Summary Table:**

	November 2015				December 2015	January 2016	February 2016				March 2016				
	WW	45	46	47			48	05	06	07	08	09	10	11	12
Initial PCN Issue Date				X											
Qual Report Availability									X						
Final PCN Issue Date									X						
Implementation Date												X			

**Markings to Distinguish Revised from Unrevised Devices:**

Traceability code

**Revision History:**

**November 27, 2015:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

PCN\_JAON-20TVFV764\_Qual\_Plan.pdf  
PCN\_JAON-20TVFV764\_Affected\_CPN.pdf  
PCN\_JAON-20TVFV764\_Affected\_CPN.xls

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